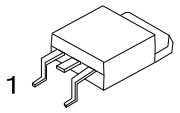
02NM65-FD

Power MOSFET

0.2A, 650V N-CHANNEL SUPER-JUNCTION MOSFET



TO-252

■ DESCRIPTION

The UTC **02NM65-FD** is an Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics.

This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

■ FEATURES

* $R_{DS(on)}$ < 19Ω @ V_{GS}=10V, I_D=0.1A
* High breakdown voltage

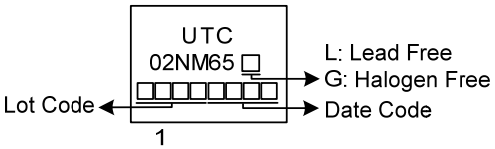
■ ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
02NM65L-TN3-R	02NM65G-TN3-R	TO-252	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

02NM65G-TN3-R (1)Packing Type (2)Package Type (3)Green Package	(1) R: Tape Reel (2) TN3: TO-252 (3) G: Halogen Free and Lead Free L: Lead Free

■ MARKING



■ ABSOLUTE MAXIMUM RATINGS (T_A =25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	±30	V
Drain Current	Continuous	I_D	0.2	A
	Pulsed	I_{DM}	0.4	A
Peak Diode Recovery dv/dt (Note 3)		dv/dt	8	V/ns
Power Dissipation		P_D	20	W
Junction Temperature		T_J	+150	°C
Storage Temperature Range		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature.
3. I_{SD} ≤ 0.2A, di/dt ≤ 200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C

■ THERMAL DATA

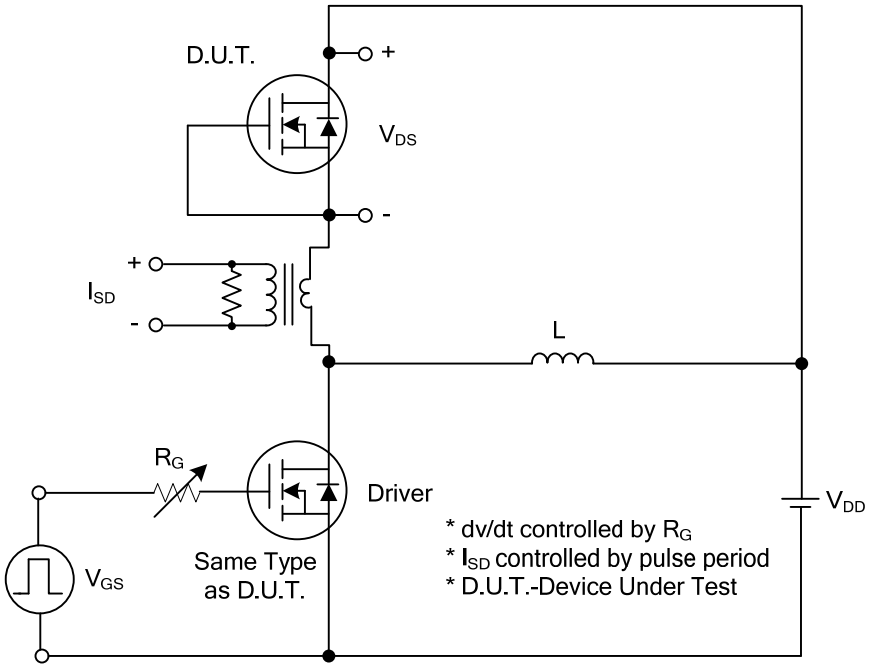
PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	110	°C/W
Junction to Case	θ_{JC}	6.25	°C/W

■ ELECTRICAL CHARACTERISTICS (T_C =25°C, unless otherwise specified)

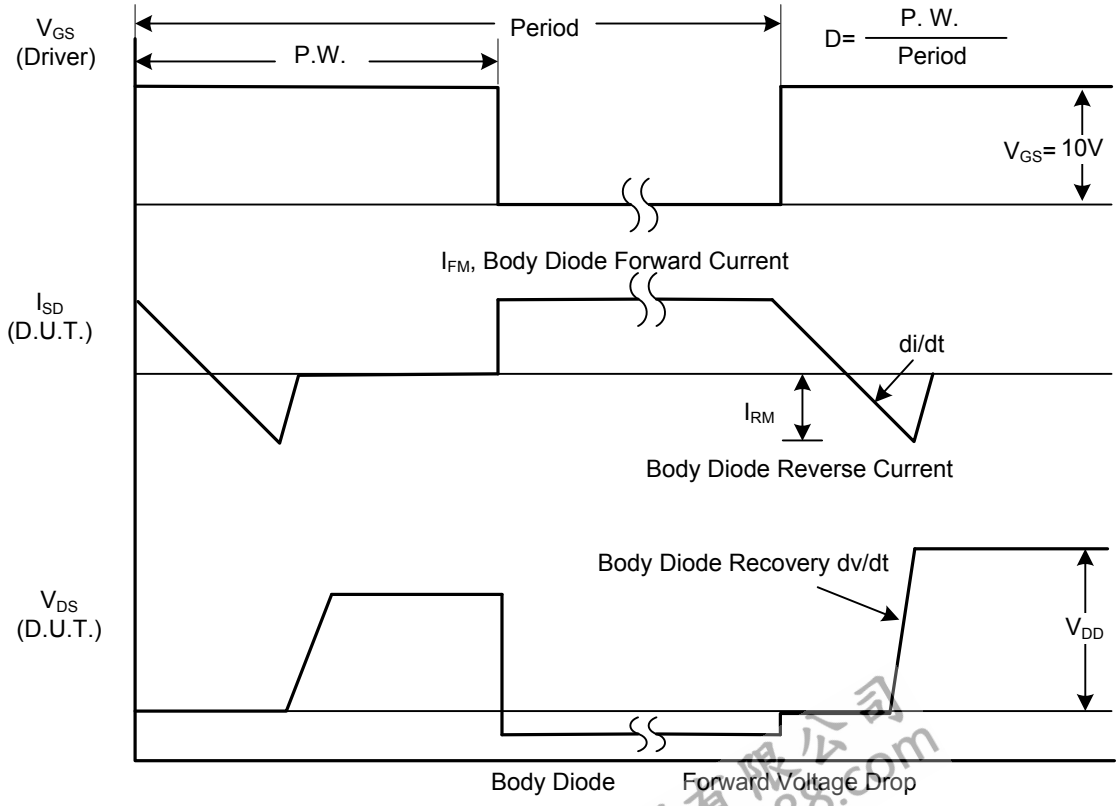
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	I_D=250μA, V_{GS}=0V	650			V
Drain-Source Leakage Current		I_{DSS}	V_{DS}=650V, V_{GS}=0V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{GS}=+30V, V_{DS}=0V			+100	nA
	Reverse		V_{GS}=-30V, V_{DS}=0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS}=V_{GS}, I_D=250μA	1.0		3.0	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS}=10V, I_D=0.1A			19	Ω
DYNAMIC PARAMETERS							
Input Capacitance		C_{ISS}	V_{GS}=0V, V_{DS}=25V, f=1.0MHz		26		pF
Output Capacitance		C_{OSS}			20		pF
Reverse Transfer Capacitance		C_{RSS}			3		pF
SWITCHING PARAMETERS							
Total Gate Charge		Q_G	V_{DS}=150V, V_{GS}=10V, I_D=0.2A, I_D=3mA (Note 1, 2)		6		nC
Gate to Source Charge		Q_{GS}			2.4		nC
Gate to Drain Charge		Q_{GD}			1.4		nC
Turn-ON Delay Time		$t_{D(ON)}$	V_{DS}=150V, V_{GS}=10V, I_D=0.2A, R_G=25Ω (Note 1, 2)		3		ns
Rise Time		t_R			6.2		ns
Turn-OFF Delay Time		$t_{D(OFF)}$			24		ns
Fall-Time		t_F			276		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Body-Diode Continuous Current		I_S				0.2	A
Maximum Body-Diode Pulsed Current		I_{SM}				0.4	A
Drain-Source Diode Forward Voltage		V_{SD}	I_S=0.2A, V_{GS}=0V			1.4	V
Body Diode Reverse Recovery Time		t_{rr}	I_S=0.2A, V_{GS}=0V, dI_F/dt=100A/μs (Note 1)		66		ns
Body Diode Reverse Recovery Charge		Q_{rr}			0.07		μC

Notes: 1. Pulse Test: Pulse width ≤ 300μs, Duty cycle≤2%.
2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

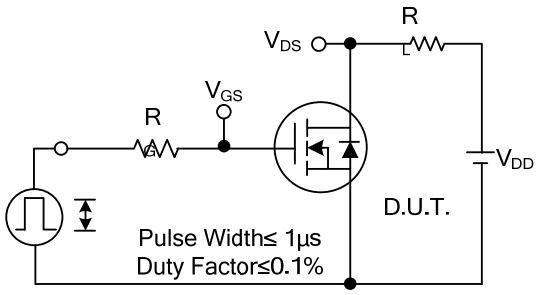


Peak Diode Recovery dv/dt Test Circuit

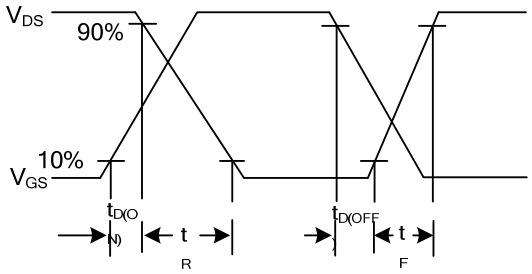


Peak Diode Recovery dv/dt Waveforms

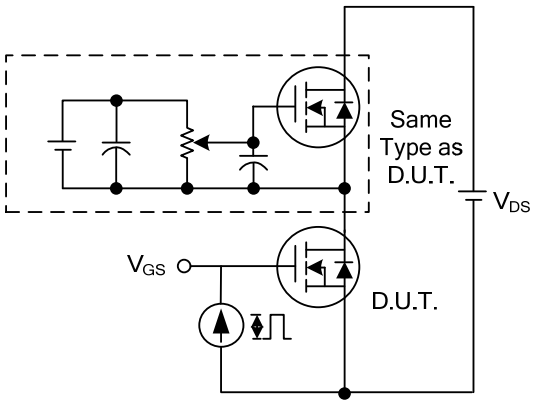
■ TEST CIRCUITS AND WAVEFORMS



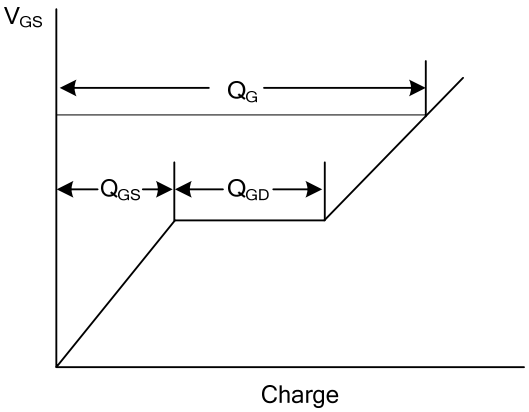
Switching Test Circuit



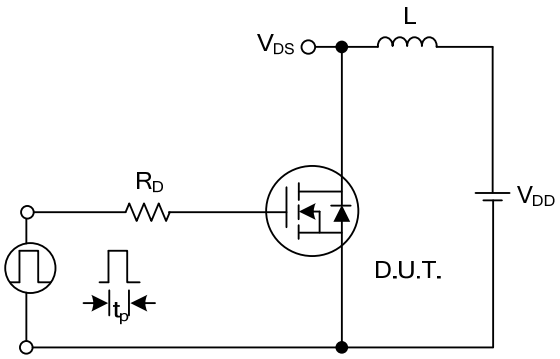
Switching Waveforms



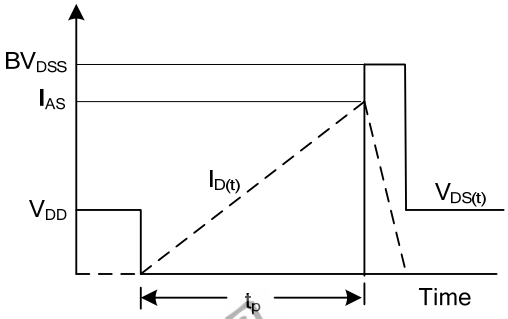
Gate Charge Test Circuit



Gate Charge Waveform



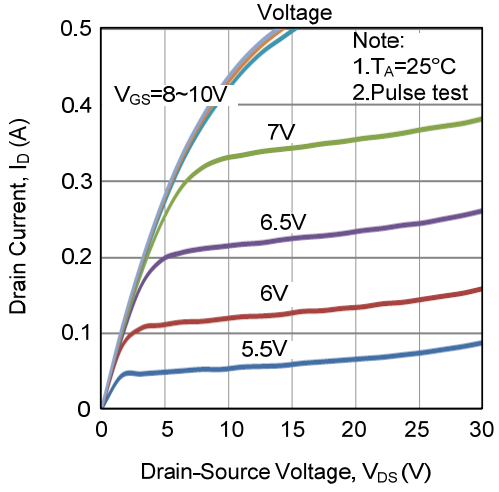
Unclamped Inductive Switching Test Circuit



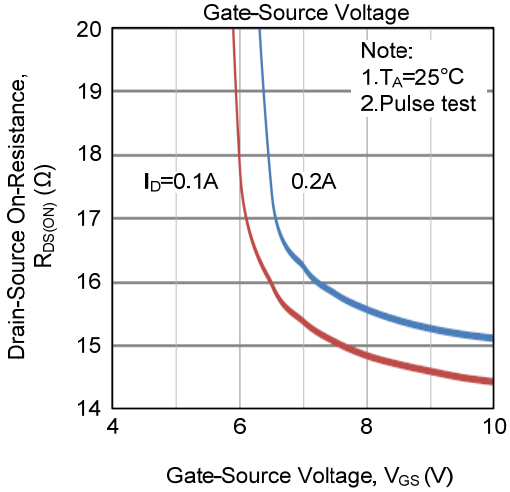
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

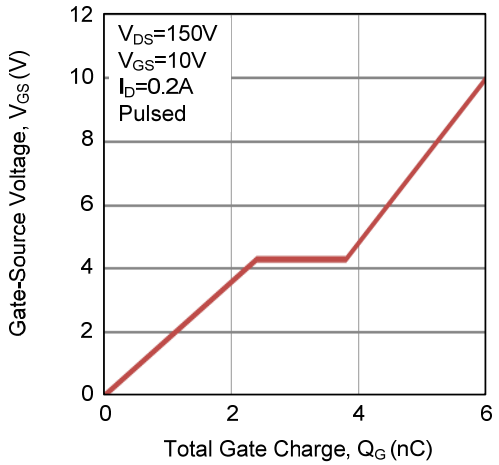
Drain Current vs. Drain-Source Voltage



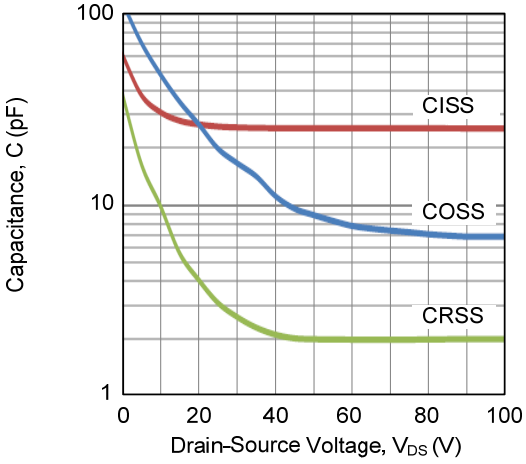
Drain-Source On-Resistance vs. Gate-Source Voltage



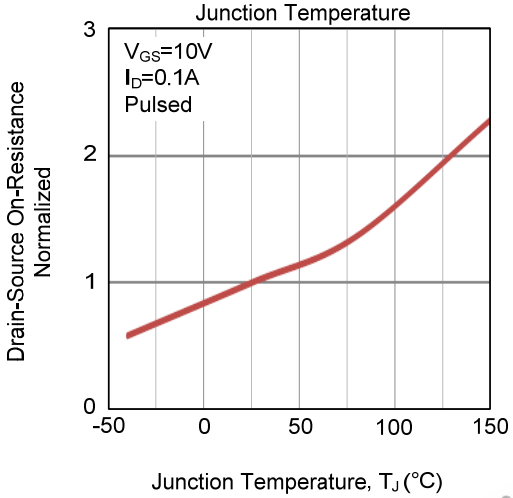
Gate Charge Characteristics



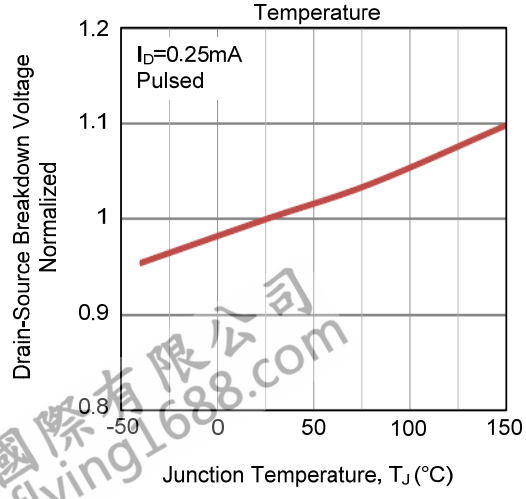
Capacitance Characteristics



Drain-Source On-Resistance vs. Junction Temperature

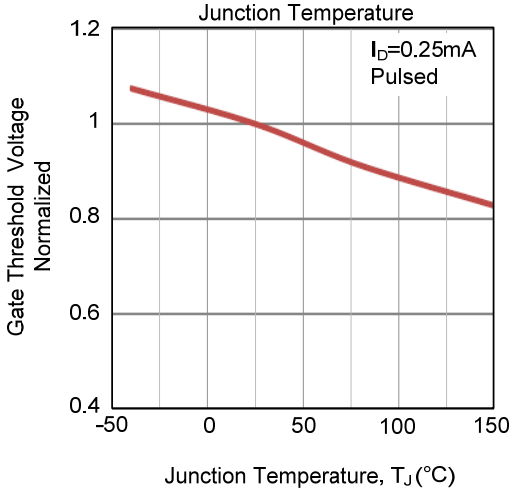


Breakdown Voltage vs. Junction Temperature

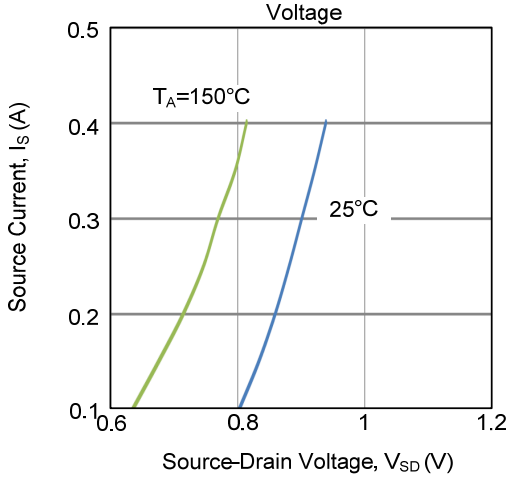


■ TYPICAL CHARACTERISTICS (Cont.)

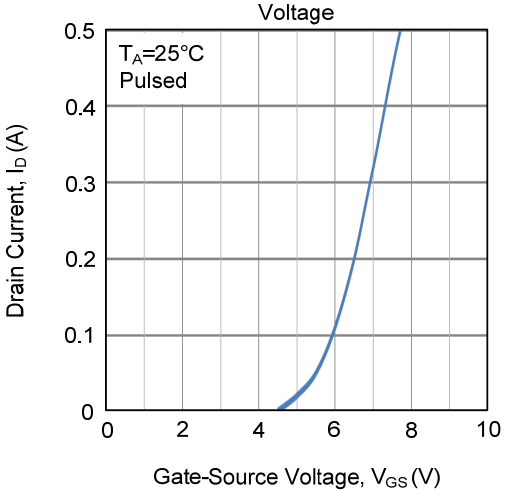
Gate Threshold Voltage vs. Junction Temperature



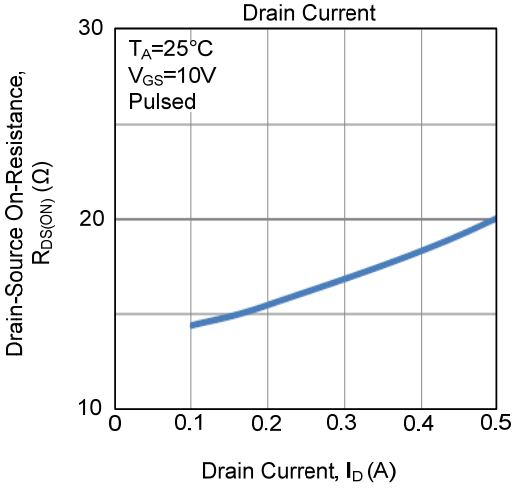
Source Current vs. Source-Drain Voltage



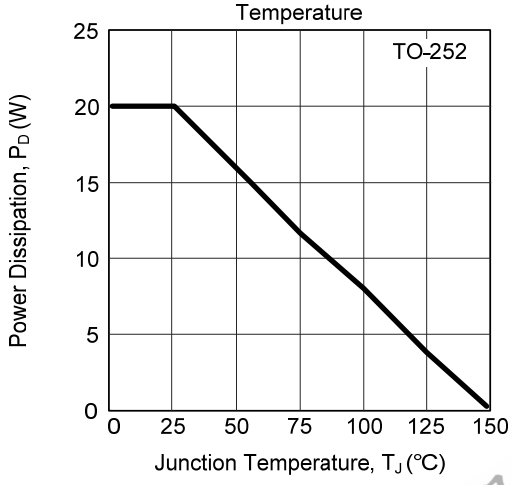
Drain Current vs. Gate-Source Voltage



Drain-Source On-Resistance vs. Drain Current



Power Dissipation vs. Junction Temperature



Safe Operating Area